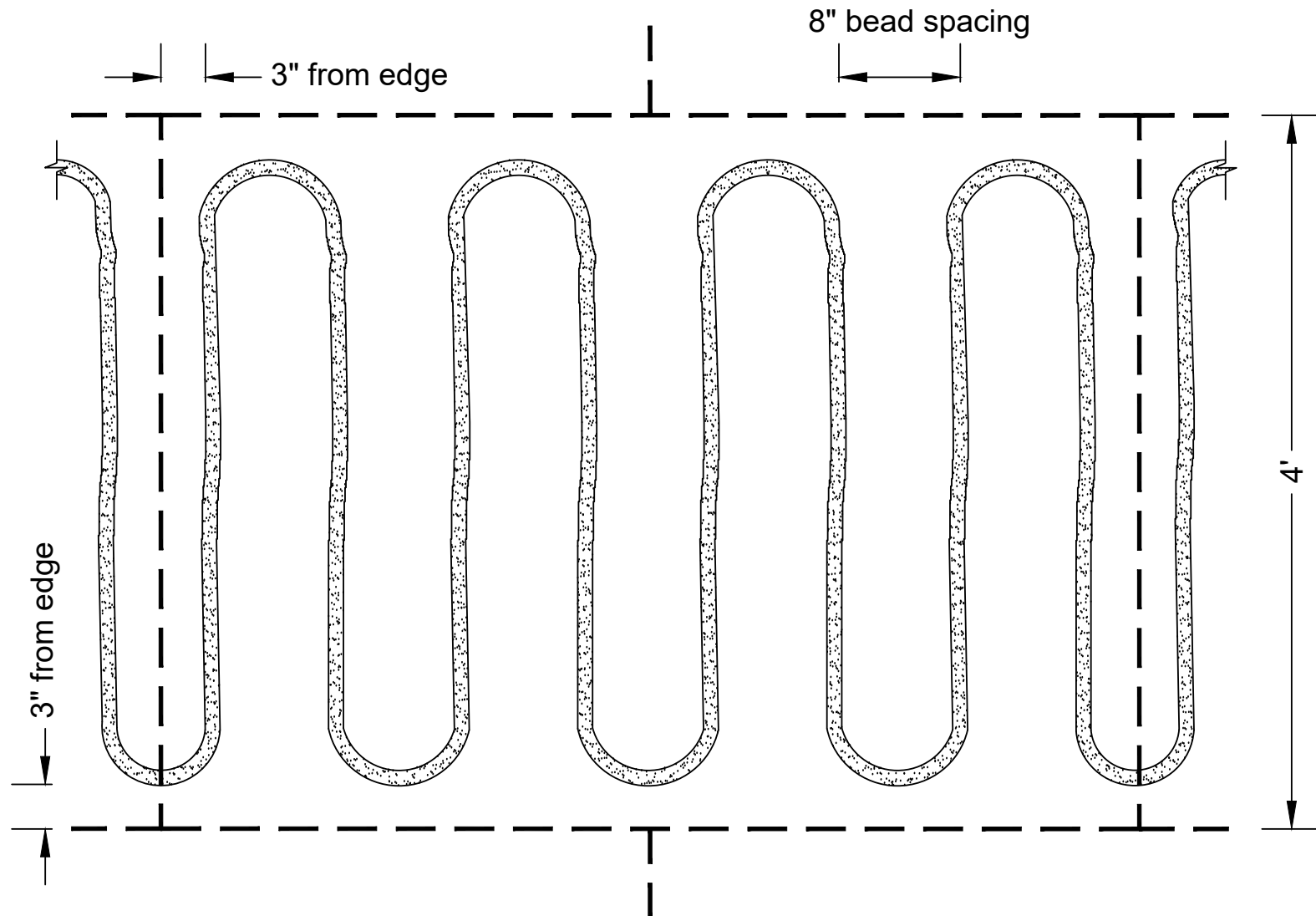


PARA-STIK & PARAFAST BEAD SPACING

4' X 4' INSULATION PANEL
8" BEAD SPACING



- NOTES: 1. THE ABOVE BEAD SPACING FREQUENCY IS INTENDED AS A GUIDELINE FOR INSULATION ADHESION BELOW SIPLAST MEMBRANE SYSTEMS AND IS SUBJECT TO SIPLAST AND INDUSTRY STANDARD REQUIREMENTS.
2. BOARDS MAY RISE FOLLOWING APPLICATION OF BEADS AT 8-INCHES O.C. DUE TO POST GROWTH OF THE ADHESIVE AND MAY REQUIRE REPEATED WALK-IN OR TEMPORARY BALLAST UNTIL THE ADHESIVE CURES.

N.T.S.